

1 Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"]
FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. SnPb plating.

2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).


3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.). Contact material- BeCu; finish 0.25 μ m [10 μ] Au over 2.54 μ m [100 μ] Ni (min.).

4 Test points: material- Phosphor Bronze; plating- Sn over 1.27 μ m [50 μ] Ni. Gold flash on contact end.

Description: Carrier Adaptor (CA)

52 position(0.65mm pitch) QFP Zero Insertion Force socket with test points to leadless surface mount foot.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

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| CA-QFE52SA-L-Z-T-01 Drawing | | Status: Released | Scale 2:1 | Rev: C |
|  <p>© 1996 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p> | Drawing: V. Thao | | Date: 11/13/96 | |
| | File: CA-QFE52SA-L-Z-T-01 Dwg | | Modified: 7/17/01 | |